

Parker Chomerics Tecknit Teckfip™ FIP-C (SP) Formed in Place Conductive Elastomer

Category : Polymer

Material Notes:

Description: This is the small particle version of the FIP-C compound. It was specifically designed for mobile cell phone applications, which require a high degree of EMI shielding. While the compound has been optimized for its overall shielding effectiveness, high cycling applications are not recommended for this material. This compound is ideally designed for projects that will not get opened and closed frequently, such as mobile phones. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-Tecknit-Teckfip-FIP-C-SP-Formed-in-Place-Conductive-Elastomer.php

Physical Properties	Metric	English	Comments
Specific Gravity	1.794 - 2.427 g/cc	1.794 - 2.427 g/cc	

Mechanical Properties	Metric	English	Comments
Hardness, Shore A	50 - 60	50 - 60	
Tensile Strength	>= 1.08 MPa	>= 157 psi	
Elongation at Break	31 %	31 %	
Peel Strength	>= 9.00 kN/m	>= 51.4 pli	
Compression Set	10 - 25 %	10 - 25 %	
	57 %	57 %	
	@Temperature 70.0 °C, Time 79200 sec	@Temperature 158 °F, Time 22.0 hour	

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	125 °C	257 °F	
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	0.018 ohm-cm	0.018 ohm-cm	
Surface Resistance	<= 0.010 ohm	<= 0.010 ohm	

Processing Properties	Metric	English	Comments
Dry Time	>= 0.100 hour	>= 0.100 hour	Tack Free

Cure Time Processing Properties	<= 1440 min Metric	<= 24.0 hour English	Comments
Shelf Life	1.00 Month	1.00 Month	Syringe
	6.00 Month	6.00 Month	Cartridge

Descriptive Properties	Value	Comments
Color	Beige	
Filler	Silver/Copper	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com
Email : sales@lookpolymers.com
Tel : +86 021-51131842
Mobile : +86 13061808058
Skype : lookpolymers
Address : United North Road 215,Fengxian District, Shanghai City,China